

# DMA56406

## Silicon PNP epitaxial planar type

For digital circuits  
DMA26406 in SMini6 type package

## ■ Features

- High forward current transfer ratio  $h_{FE}$  with excellent linearity
- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

## ■ Marking Symbol: L7

## ■ Basic Part Number

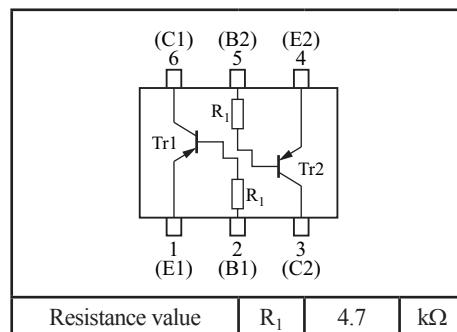
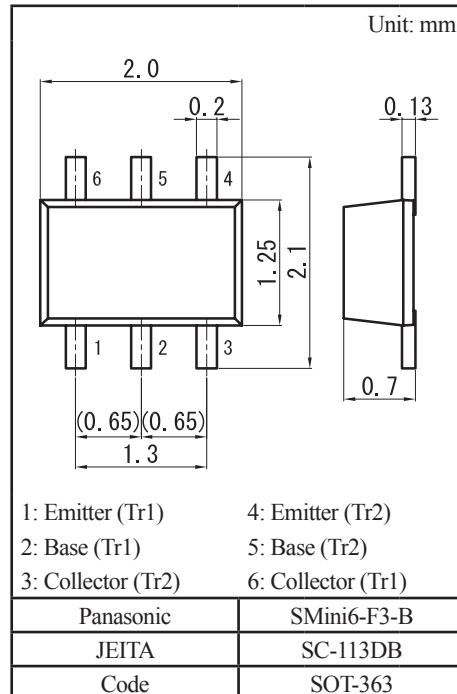
### Dual DRA2143T (Individual)

## ■ Packaging

DMA564060R Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

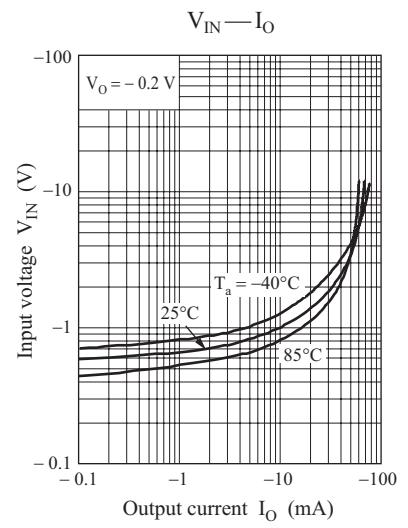
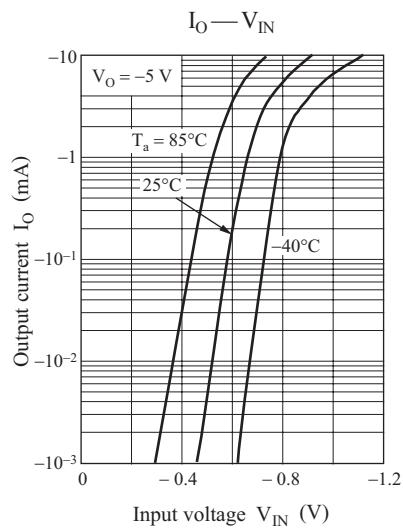
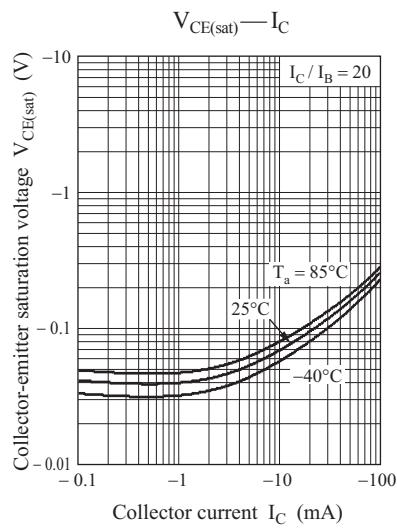
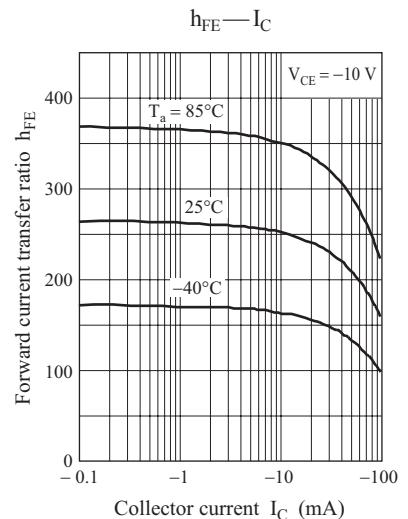
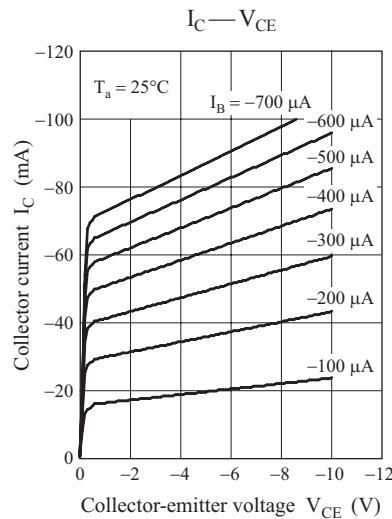
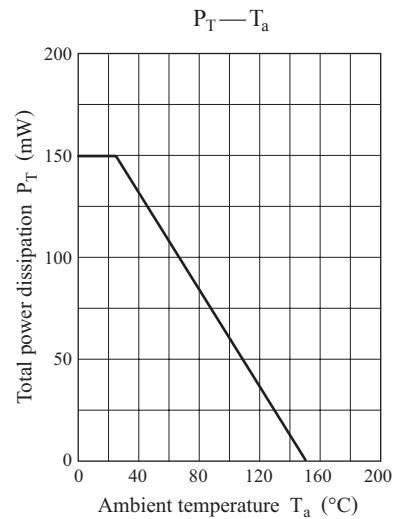
| Parameter  |                                       | Symbol           | Rating      | Unit |
|------------|---------------------------------------|------------------|-------------|------|
| Tr1<br>Tr2 | Collector-base voltage (Emitter open) | V <sub>CBO</sub> | -50         | V    |
|            | Collector-emitter voltage (Base open) | V <sub>CEO</sub> | -50         | V    |
|            | Collector current                     | I <sub>C</sub>   | -100        | mA   |
| Overall    | Total power dissipation               | P <sub>T</sub>   | 150         | mW   |
|            | Junction temperature                  | T <sub>j</sub>   | 150         | °C   |
|            | Operating ambient temperature         | T <sub>opr</sub> | -40 to +85  | °C   |
|            | Storage temperature                   | T <sub>stg</sub> | -55 to +150 | °C   |



## ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

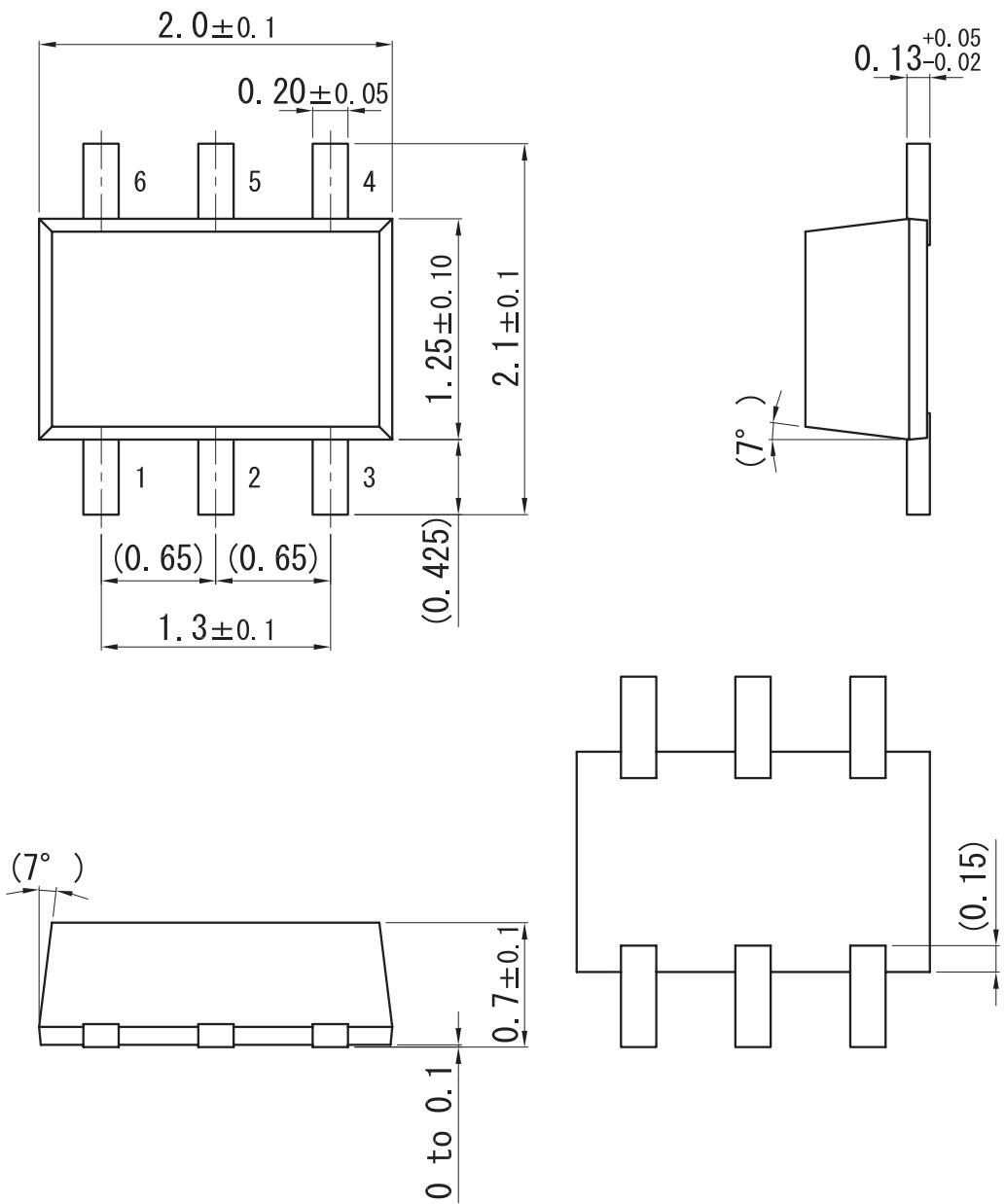
| Parameter                                    | Symbol        | Conditions                        | Min  | Typ | Max   | Unit      |
|--|---------------|-----------------------------------|------|-----|-------|-----------|
| Collector-base voltage (Emitter open)        | $V_{CBO}$     | $I_C = -10 \mu A, I_E = 0$        | -50  |     |       | V         |
| Collector-emitter voltage (Base open)        | $V_{CEO}$     | $I_C = -2 mA, I_B = 0$            | -50  |     |       | V         |
| Collector-base cutoff current (Emitter open) | $I_{CBO}$     | $V_{CB} = -50 V, I_E = 0$         |      |     | -0.1  | $\mu A$   |
| Collector-emitter cutoff current (Base open) | $I_{CEO}$     | $V_{CE} = -50 V, I_B = 0$         |      |     | -0.5  | $\mu A$   |
| Emitter-base cutoff current (Collector open) | $I_{EBO}$     | $V_{EB} = -6 V, I_C = 0$          |      |     | -0.01 | mA        |
| Forward current transfer ratio               | $h_{FE}$      | $V_{CE} = -10 V, I_C = -5 mA$     | 160  |     | 460   | —         |
| Collector-emitter saturation voltage         | $V_{CE(sat)}$ | $I_C = -10 mA, I_B = -0.5 mA$     |      |     | -0.25 | V         |
| Input voltage (ON)                           | $V_{I(on)}$   | $V_{CE} = -0.2 V, I_C = -5 mA$    | -1.0 |     |       | V         |
| Input voltage (OFF)                          | $V_{I(off)}$  | $V_{CE} = -5 V, I_C = -100 \mu A$ |      |     | -0.4  | V         |
| Input resistance                             | $R_I$         |                                   | -30% | 4.7 | +30%  | $k\Omega$ |

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

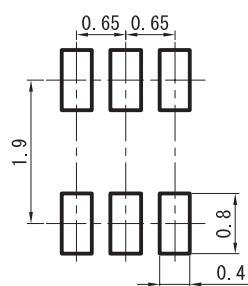


## SMini6-F3-B

Unit: mm



## ■ Land Pattern (Reference) (Unit: mm)



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